

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	ADG/22/13856
1.3 Title of PCN	DPAK Big Die Dual Die line Transfer from Shenzhen to Tongfu Microelectronics (China)
1.4 Product Category	Power MOSFET HV – IGBT – Power Bipolar
1.5 Issue date	2022-12-22

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio GIUDICE, Angelo RAO
2.1.2 Marketing Manager	Paolo PETRALI, Natale Sandro D'ANGELO
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Tongfu Microelectronics (China)

4. Description of change

	Old	New
4.1 Description	DPAK Big Die Dual Die products are manufactured in Shenzhen (China)	DPAK Big Die Dual Die products are manufactured in Tongfu Microelectronics (China)
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	CAPACITY INCREASE
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	By internal traceability and dedicated FG code
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7. Timing / schedule

7.1 Date of qualification results	2022-12-19
7.2 Intended start of delivery	2023-04-21
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13856 Binder1.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2022-12-22

9. Attachments (additional documentations)

13856 Public product.pdf
 13856 13856-DPAK Big Die Dual Die line Transfer from Shenzhen to TFME - IND.pdf
 13856 Binder1.pdf
 13856 Comparison DPAK A2 STS vs TFME C3.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STD10LN80K5	
	STD10N60DM2	
	STD10NM60ND	
	STD11N60DM2	
	STD11NM50N	
	STD11NM60ND	
	STD11NM65N	
	STD12N50DM2	
	STD12N50M2	
	STD12N60M2	
	STD12N65M2	
	STD13N60DM2	
	STD13N65M2	
	STD13NM60ND	
	STD15N60M2-EP	
	STD16N65M2	
	STD18N60M6	
	STD5N52U	
	STD5N95K3	
STD5NM60T4	STD5NM60T4	
	STD6N80K5	
	STD7LN80K5	
	STD7N90K5	
STD7NK40ZT4	STD7NK40ZT4	
	STD7NM80	
	STD80N240K6	
	STD80N340K6	
	STD8N60DM2	
	STD901T	
	STGD10NC60KDT4	
STGD5NB120SZT4	STGD5NB120SZT4	
	STGD6M65DF2	
STGD7NB60ST4	STGD7NB60ST4	
	STGD8NC60KDT4	

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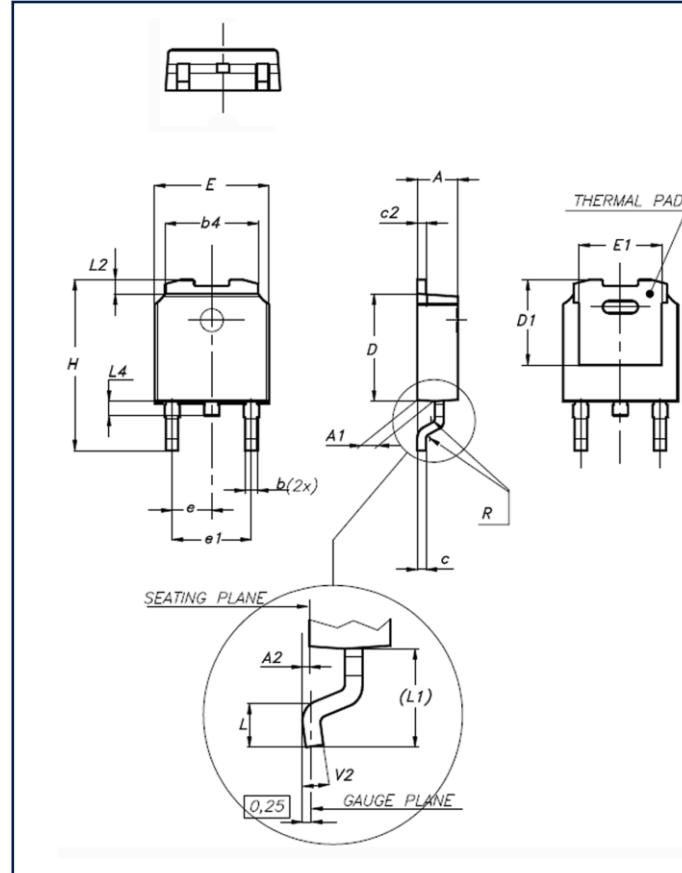
Comparison DPAK Shenzhen vs TFME

Shenzhen (type A2)

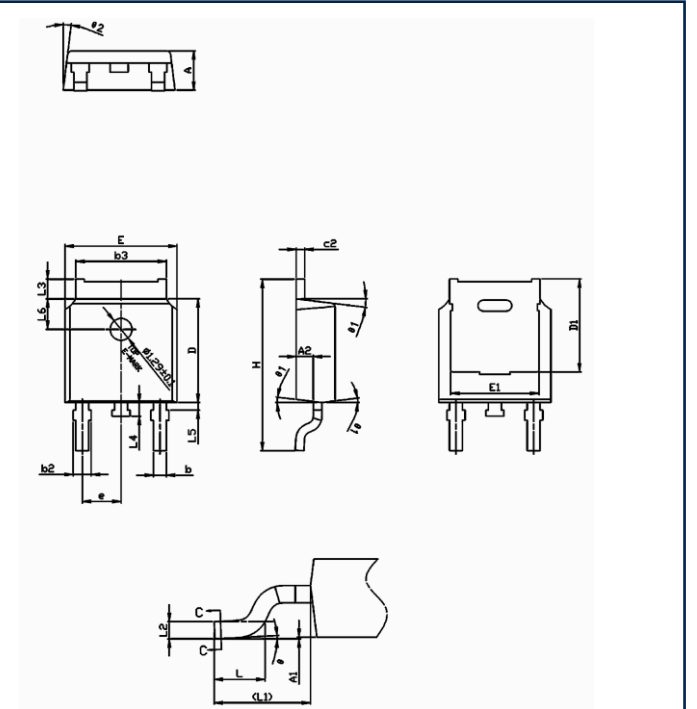
TFME (type C3)

Dim.	mm			Dim.	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	2.20		2.40	A	2.20	2.30	2.38
A1	0.90		1.10	A1	0.00		0.10
A2	0.03		0.23	A2	0.90	1.01	1.10
b	0.64		0.90	b	0.72		0.85
				b2	0.72		1.10
				b3	5.13	5.33	5.46
b4	5.20		5.40				
c	0.45		0.60	c	0.47		0.60
c2	0.48		0.60	c2	0.47		0.60
D	6.00		6.20	D	6.00	6.10	6.20
D1	4.95	5.10	5.25	D1	5.15	5.40	5.65
E	6.40		6.60	E	6.50	6.60	6.70
E1	5.10	5.20	5.30	E1	5.00	5.20	5.40
e	2.159	2.286	2.413	e	2.186	2.286	2.386
e1	4.445	4.572	4.699				
H	9.35		10.10	H	9.80	10.10	10.40
L	1.00		1.50	L	1.40	1.50	1.70
(L1)	2.60	2.80	3.00	L1	2.90 REF		
L2	0.65	0.80	0.95	L2	0.51 BSC		
				L3	0.90		1.25
L4	0.60		1.00	L4	0.60	0.80	1.00
				L5	0.15		0.75
				L6	1.80 REF		
				Θ	0°		8°
R		0.2		Θ 1	5°	7°	9°
V2	0°		8°	Θ 2	5°	7°	9°

Shenzhen (Current)



TFME (New)





Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : DPAK Big Die Dual Die line Transfer from Shenzhen to Tongfu Microelectronics (China)

PCN Reference : ADG/22/13856

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STD11NM65N	STD15N60M2-EP	STD13N60DM2
STD5NM60T4	STGD7NB60ST4	STGD6M65DF2
STD12N50DM2	STD11N60DM2	STGD10NC60KDT4
STD11NM50N	STD8N60DM2	STD10LN80K5
STGD5NB120SZT4	STD5N95K3	STD901T
STD7LN80K5	STGD8NC60KDT4	STD12N50M2
STD7NM80	STD12N60M2	STD7N90K5
STD13N65M2	STD12N65M2	STD16N65M2
STD7NK40ZT4	STD80N450K6	STD5N52U
STD18N60M6	STD80N240K6	STD6N80K5
STD80N340K6	STD10N60DM2	

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